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**TEXAS
INSTRUMENTS**

SN54LVC541A, SN74LVC541A

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SNx4LVC541A Octal Buffers/Drivers With 3-State Outputs

1 Features

- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.1 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
<0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot)
>2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- I_{off} Supports Live Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

2 Applications

- Servers
- PCs and Notebooks
- Network Switches
- Wearable Health and Wellness Devices
- Telecom Infrastructures
- Electronic Points of Sale

3 Description

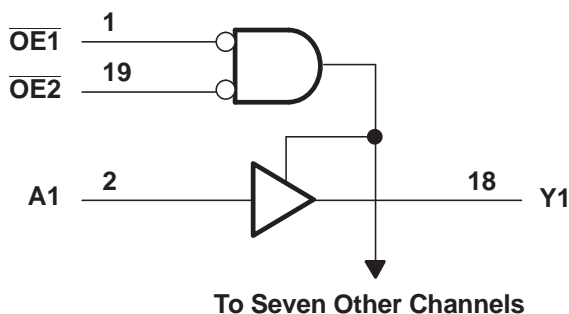
The SN54LVC541A octal buffer/driver is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC541A octal buffer/driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|--------------------|
| SN74LVC541A | SSOP (20) | 7.20 mm × 5.30 mm |
| | TVSOP (20) | 5.00 mm × 4.40 mm |
| | VQFN (20) | 4.50 mm × 3.50 mm |
| | SOIC (20) | 12.80 mm × 7.50 mm |
| | TSSOP (20) | 6.50 mm × 4.40 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

SN54LVC541A, SN74LVC541A

SCAS298N – JANUARY 1993 – REVISED JUNE 2014

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Table of Contents

| | | | |
|---|----------|--|-----------|
| 1 Features | 1 | 9 Detailed Description | 10 |
| 2 Applications | 1 | 9.1 Overview | 10 |
| 3 Description | 1 | 9.2 Functional Block Diagram | 10 |
| 4 Simplified Schematic | 1 | 9.3 Feature Description | 10 |
| 5 Revision History | 2 | 9.4 Device Functional Modes | 10 |
| 6 Pin Configuration and Functions | 3 | 10 Application and Implementation | 11 |
| 7 Specifications | 4 | 10.1 Application Information | 11 |
| 7.1 Absolute Maximum Ratings | 4 | 10.2 Typical Application | 11 |
| 7.2 Handling Ratings | 4 | 11 Power Supply Recommendations | 12 |
| 7.3 Recommended Operating Conditions | 5 | 12 Layout | 12 |
| 7.4 Thermal Information | 5 | 12.1 Layout Guidelines | 12 |
| 7.5 Electrical Characteristics—DC Limit Changes | 6 | 12.2 Layout Example | 12 |
| 7.6 Switching Characteristics—AC Limit Changes | 7 | 13 Device and Documentation Support | 13 |
| 7.7 Switching Characteristics, SN74LVC541A –40°C to 85°C | 7 | 13.1 Related Links | 13 |
| 7.8 Switching Characteristics, SN74LVC541A –40°C to 125°C | 7 | 13.2 Trademarks | 13 |
| 7.9 Operating Characteristics | 7 | 13.3 Electrostatic Discharge Caution | 13 |
| 7.10 Typical Characteristics | 8 | 13.4 Glossary | 13 |
| 8 Parameter Measurement Information | 9 | 14 Mechanical, Packaging, and Orderable Information | 13 |

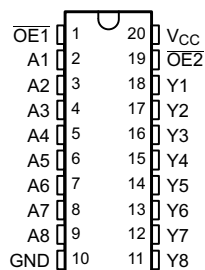
5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

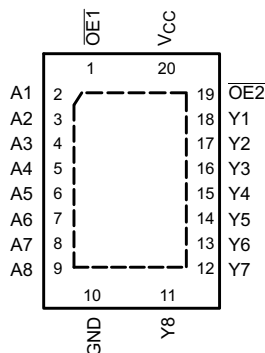
| Changes from Revision M (May 2005) to Revision N | Page |
|--|------|
| • Updated document to new TI data sheet format. | 1 |
| • Removed Ordering Information table. | 1 |
| • Updated I_{off} Feature bullet. | 1 |
| • Updated Features to include Military Disclaimer. | 1 |
| • Added Applications | 1 |
| • Added Device Information table. | 1 |
| • Added Handling Ratings table. | 4 |
| • Changed MAX operating free-air temperature from 85°C to 125°C for SN74LVC541A. | 5 |
| • Updated Thermal Information table. | 5 |
| • Added –40°C TO 125°C temperature range to Electrical Characteristics table for SN74LVC541A. | 6 |
| • Added Switching Characteristics table –40°C TO 125°C temperature range for SN74LVC541A. | 7 |
| • Added Typical Characteristics. | 8 |

6 Pin Configuration and Functions

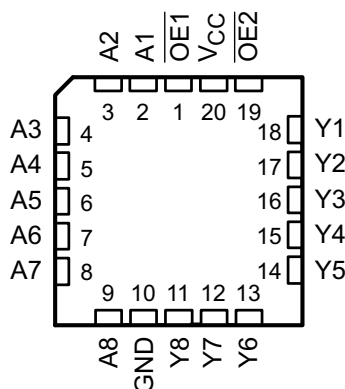
SN54LVC541A . . . J OR W PACKAGE
SN74LVC541A . . . DB, DGV, DW, NS,
OR PW PACKAGE
(TOP VIEW)



SN74LVC541A . . . RGY PACKAGE
(TOP VIEW)



SN54LVC541A . . . FK PACKAGE
(TOP VIEW)



Pin Functions

| PIN | | I/O | DESCRIPTION |
|-----|------------------|-----|---------------|
| NO. | NAME | | |
| 1 | $\overline{OE1}$ | I | Output enable |
| 2 | A1 | I | A1 input |
| 3 | A2 | I | A2 input |
| 4 | A3 | I | A3 input |
| 5 | A4 | I | A4 input |
| 6 | A5 | I | A5 input |
| 7 | A6 | I | A6 input |
| 8 | A7 | I | A7 input |
| 9 | A8 | I | A8 input |
| 10 | GND | — | Ground pin |
| 11 | Y8 | O | Y8 output |
| 12 | Y7 | O | Y7 output |
| 13 | Y6 | O | Y6 output |
| 14 | Y5 | O | Y5 output |
| 15 | Y4 | O | Y4 output |
| 16 | Y3 | O | Y3 output |
| 17 | Y2 | O | Y2 output |
| 18 | Y1 | O | Y1 output |
| 19 | $\overline{OE2}$ | I | Output enable |
| 20 | VCC | — | Power pin |

SN54LVC541A, SN74LVC541A

SCAS298N – JANUARY 1993 – REVISED JUNE 2014

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7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|-----------------|---|--------------------|-----------------------|---------|
| V _{CC} | Supply voltage range | –0.5 | 6.5 | V |
| V _I | Input voltage range ⁽²⁾ | –0.5 | 6.5 | V |
| V _O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | –0.5 | 6.5 | V |
| V _O | Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾ | –0.5 | V _{CC} + 0.5 | V |
| I _{IK} | Input clamp current | V _I < 0 | | –50 mA |
| I _{OK} | Output clamp current | V _O < 0 | | –50 mA |
| I _O | Continuous output current | | | ±50 mA |
| | Continuous current through V _{CC} or GND | | | ±100 mA |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} is provided in the *Recommended Operating Conditions* table.

7.2 Handling Ratings

| | | | MIN | MAX | UNIT |
|--------------------|---------------------------|--|-----|------|------|
| T _{stg} | Storage temperature range | | –65 | 150 | °C |
| V _(ESD) | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾ | 0 | 2000 | V |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾ | 0 | 1000 | |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | | SN54LVC541A | | SN74LVC541A | | UNIT |
|-----------------|--------------------------------|------------------------------------|-------------|-----------------|------------------------|-----------------|------|
| | | | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | Operating | 2 | 3.6 | 1.65 | 3.6 | V |
| | | Data retention only | 1.5 | | 1.5 | | |
| V _{IH} | High-level input voltage | V _{CC} = 1.65 V to 1.95 V | | | 0.65 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | | | 1.7 | | |
| | | V _{CC} = 2.7 V to 3.6 V | 2 | | 2 | | |
| V _{IL} | Low-level input voltage | V _{CC} = 1.65 V to 1.95 V | | | 0.35 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | | | 0.7 | | |
| | | V _{CC} = 2.7 V to 3.6 V | | 0.8 | | 0.8 | |
| V _I | Input voltage | | 0 | 5.5 | 0 | 5.5 | V |
| V _O | Output voltage | High or low state | 0 | V _{CC} | 0 | V _{CC} | V |
| | | 3-state | 0 | 5.5 | 0 | 5.5 | |
| I _{OH} | High-level output current | V _{CC} = 1.65 V | | | | –4 | mA |
| | | V _{CC} = 2.3 V | | | | –8 | |
| | | V _{CC} = 2.7 V | | –12 | | –12 | |
| | | V _{CC} = 3 V | | –24 | | –24 | |
| I _{OL} | Low-level output current | V _{CC} = 1.65 V | | | | 4 | mA |
| | | V _{CC} = 2.3 V | | | | 8 | |
| | | V _{CC} = 2.7 V | | 12 | | 12 | |
| | | V _{CC} = 3 V | | 24 | | 24 | |
| T _A | Operating free-air temperature | | –55 | 125 | –40 | 125 | °C |

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

7.4 Thermal Information

over operating free-air temperature range (unless otherwise noted)

| THERMAL METRIC ⁽¹⁾ | | SN74LVC541A | | | | | UNIT |
|-------------------------------|--|-------------|-------|------|------|-------|------|
| | | DB | DGV | DW | NS | PW | |
| | | 20 PINS | | | | | |
| R _{θJA} | Junction-to-ambient thermal resistance | 112.1 | 128.9 | 99.4 | 90.3 | 100.8 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 73.6 | 43.8 | 66.9 | 56.6 | 35.2 | |
| R _{θJB} | Junction-to-board thermal resistance | 67.3 | 70.4 | 66.9 | 57.8 | 51.8 | |
| ψ _{JT} | Junction-to-top characterization parameter | 33.3 | 3.2 | 33.8 | 28.7 | 2.2 | |
| ψ _{JB} | Junction-to-board characterization parameter | 66.9 | 69.7 | 66.5 | 57.4 | 51.2 | |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | n/a | n/a | n/a | n/a | n/a | |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, literature number [SPRA953](#).

SN54LVC541A, SN74LVC541A

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7.5 Electrical Characteristics—DC Limit Changes

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | –55°C TO 125°C | | | –40°C TO 85°C | | | –40°C TO 125°C | | | UNIT |
|------------------|---|-----------------|-----------------------|--------------------|-----|-----------------------|--------------------|-----|-----------------------|--------------------|-----|------|
| | | | SN54LVC541A | | | SN74LVC541A | | | SN74LVC541A | | | |
| | | | MIN | TYP ⁽¹⁾ | MAX | MIN | TYP ⁽¹⁾ | MAX | MIN | TYP ⁽¹⁾ | MAX | |
| V _{OH} | I _{OH} = –100 μA | 1.65 V to 3.6 V | | | | V _{CC} – 0.2 | | | V _{CC} – 0.3 | | | V |
| | | 2.7 V to 3.6 V | V _{CC} – 0.2 | | | | | | | | | |
| | I _{OH} = –4 mA | 1.65 V | | | | 1.20 | | | 1.20 | | | |
| | I _{OH} = –8 mA | 2.3 V | | | | 1.7 | | | 1.7 | | | |
| | I _{OH} = –12 mA | 2.7 V | 2.2 | | | 2.2 | | | 2.2 | | | |
| | | 3 V | 2.4 | | | 2.4 | | | 2.4 | | | |
| | I _{OH} = –24 mA | 3 V | 2.2 | | | 2.2 | | | 2.2 | | | |
| V _{OL} | I _{OL} = 100 μA | 1.65 V to 3.6 V | | | | 0.2 | | | 0.3 | | | V |
| | | 2.7 V to 3.6 V | 0.2 | | | | | | | | | |
| | I _{OL} = 4 mA | 1.65 V | | | | 0.45 | | | 0.45 | | | |
| | I _{OL} = 8 mA | 2.3 V | | | | 0.7 | | | 0.7 | | | |
| | I _{OL} = 12 mA | 2.7 V | 0.4 | | | 0.4 | | | 0.4 | | | |
| | I _{OL} = 24 mA | 3 V | 0.55 | | | 0.55 | | | 0.55 | | | |
| I _I | V _I = 0 to 5.5 V | 3.6 V | ±5 | | | ±5 | | | ±5 | | | μA |
| I _{off} | V _I or V _O = 5.5 V | 0 | | | | ±10 | | | ±10 | | | μA |
| I _{OZ} | V _O = 0 to 5.5 V | 3.6 V | ±15 | | | ±10 | | | ±10 | | | μA |
| I _{CC} | V _I = V _{CC} or GND | 3.6 V | 10 | | | 10 | | | 10 | | | μA |
| | 3.6 V ≤ V _I ≤ 5.5 V ⁽²⁾ | | 10 | | | 10 | | | 10 | | | |
| ΔI _{CC} | One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND | 2.7 V to 3.6 V | 500 | | | 500 | | | 500 | | | μA |
| C _i | V _I = V _{CC} or GND | 3.3 V | 4 | | | 4 | | | 4 | | | pF |
| C _o | V _O = V _{CC} or GND | 3.3 V | 5.5 | | | 5.5 | | | 5.5 | | | pF |

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This applies in the disabled state only.

7.6 Switching Characteristics—AC Limit Changes

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN54LVC541A | | | | UNIT |
|------------------|-----------------|----------------|-------------------------|-----|---------------------------------|-----|------|
| | | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | |
| | | | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | | 5.6 | 1 | 5.1 | ns |
| t _{en} | \overline{OE} | Y | | 7.5 | 1 | 7 | ns |
| t _{dis} | \overline{OE} | Y | | 7.7 | 1 | 7 | ns |

7.7 Switching Characteristics, SN74LVC541A –40°C to 85°C

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN74LVC541A | | | | | | | | UNIT |
|--------------------|-----------------|----------------|-------------------------------------|------|------------------------------------|------|-------------------------|-----|------------------------------------|-----|------|
| | | | –40°C TO 85°C | | | | | | | | |
| | | | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 1 | 15.7 | 1 | 7.8 | 1 | 5.6 | 1.5 | 5.1 | ns |
| t _{en} | \overline{OE} | Y | 1 | 17.5 | 1 | 10.5 | 1 | 7.5 | 1.5 | 7 | ns |
| t _{dis} | \overline{OE} | Y | 1 | 16.5 | 1 | 9 | 1 | 7.7 | 1.5 | 7 | ns |
| t _{sk(o)} | | | | | | | | | | 1 | ns |

7.8 Switching Characteristics, SN74LVC541A –40°C to 125°C

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN74LVC541A | | | | | | | | UNIT |
|--------------------|-----------------|----------------|-------------------------------------|------|------------------------------------|------|-------------------------|-----|------------------------------------|-----|------|
| | | | −40°C TO 125°C | | | | | | | | |
| | | | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 1 | 16.3 | 1 | 8.3 | 1 | 6.1 | 1 | 5.6 | ns |
| t _{en} | \overline{OE} | Y | 1 | 18.5 | 1 | 11.1 | 1 | 8 | 1 | 7.5 | ns |
| t _{dis} | \overline{OE} | Y | 1 | 17.3 | 1 | 9.7 | 1 | 8.2 | 1 | 7.5 | ns |
| t _{sk(o)} | | | | | | | | | | 1.5 | ns |

7.9 Operating Characteristics

T_A = 25°C

| PARAMETER | | | TEST CONDITIONS | V _{CC} = 1.8 V | V _{CC} = 2.5 V | V _{CC} = 3.3 V | UNIT |
|-----------------|--|------------------|--------------------|-------------------------|-------------------------|-------------------------|------|
| | | | | TYP | TYP | TYP | |
| C _{pd} | Power dissipation capacitance per buffer/driver | Outputs enabled | f = 10 MHz | 65 | 58 | 33 | pF |
| | | Outputs disabled | | 2 | 2 | 2 | |

SN54LVC541A, SN74LVC541A

SCAS298N – JANUARY 1993 – REVISED JUNE 2014

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7.10 Typical Characteristics

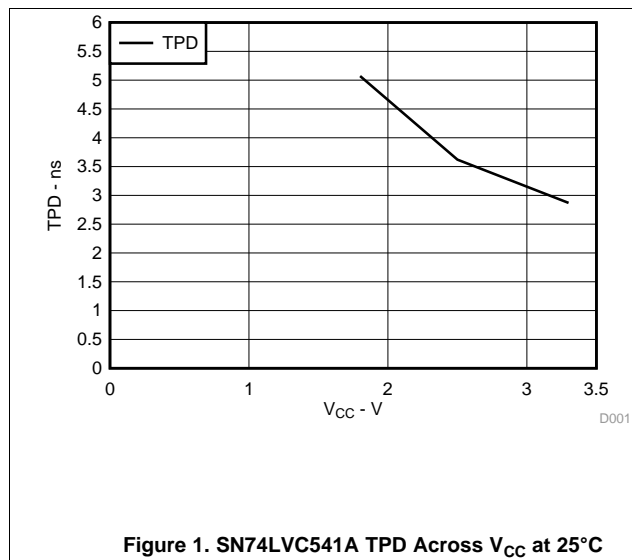


Figure 1. SN74LVC541A TPD Across V_{CC} at 25°C

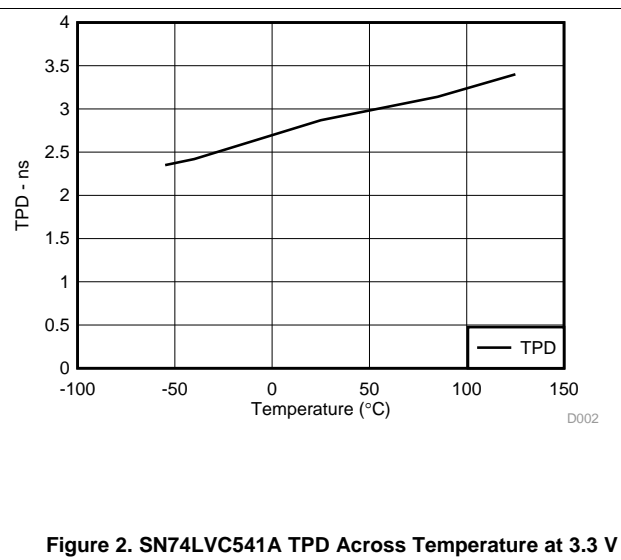
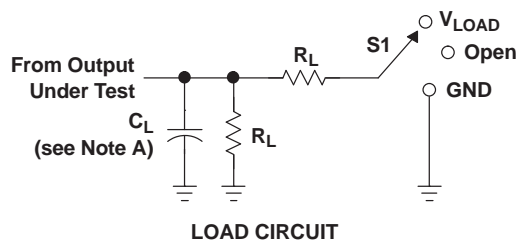


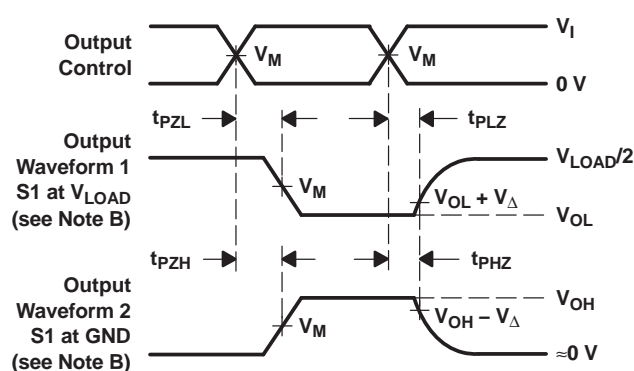
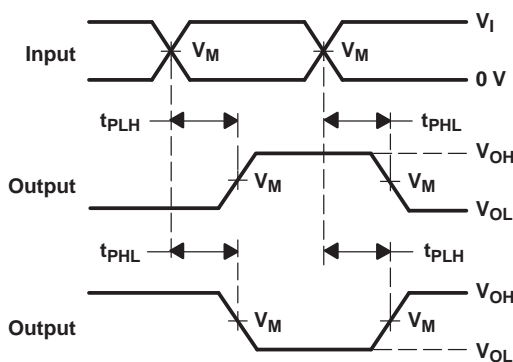
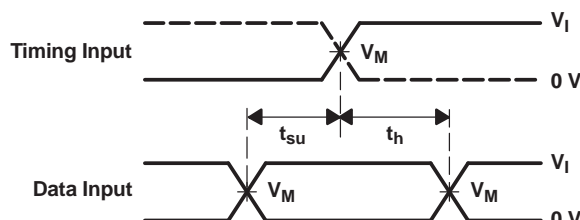
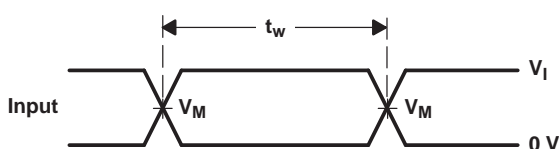
Figure 2. SN74LVC541A TPD Across Temperature at 3.3 V

8 Parameter Measurement Information



| TEST | S1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_{Δ} |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
| | V_I | t_r/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| 2.7 V | 2.7 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 2.7 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

SN54LVC541A, SN74LVC541A

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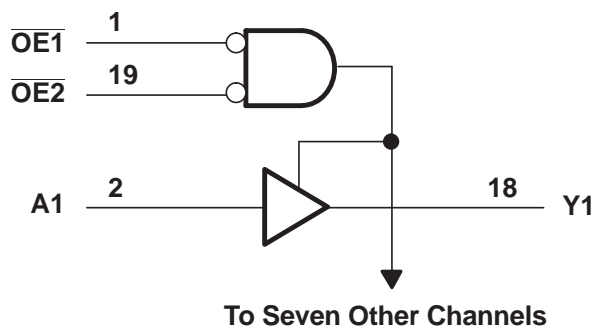
9 Detailed Description

9.1 Overview

The 'LVC541A devices are ideal for driving bus lines or buffering memory address registers.

These devices feature inputs and outputs on opposite sides of the package to facilitate printed circuit board layout. The 3-state control gate is a 2-input AND gate with active-low inputs so that, if either output enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state. Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment. These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

9.2 Functional Block Diagram



9.3 Feature Description

- Wide operating voltage range
 - Operates from 1.65 V to 3.6 V
- Allows down voltage translation
 - Inputs accept voltages to 5.5 V
- I_{off} feature
 - Allows voltages on the inputs and outputs when V_{CC} is 0 V

9.4 Device Functional Modes

Table 1. Function Table

| INPUTS | | | OUTPUT |
|------------------|------------------|---|--------|
| $\overline{OE1}$ | $\overline{OE2}$ | A | Y |
| L | L | L | L |
| L | L | H | H |
| H | X | X | Z |
| X | H | X | Z |

10 Application and Implementation

10.1 Application Information

The SN74LVC541A is a high-drive CMOS device that can be used for a multitude of bus-interface type applications where the data needs to be retained or latched. It can produce 24 mA of drive current at 3.3 V. Therefore, this device is ideal for driving multiple outputs and for high-speed applications up to 100 Mhz. The inputs are 5.5 V tolerant allowing the device to translate down to V_{CC} .

10.2 Typical Application

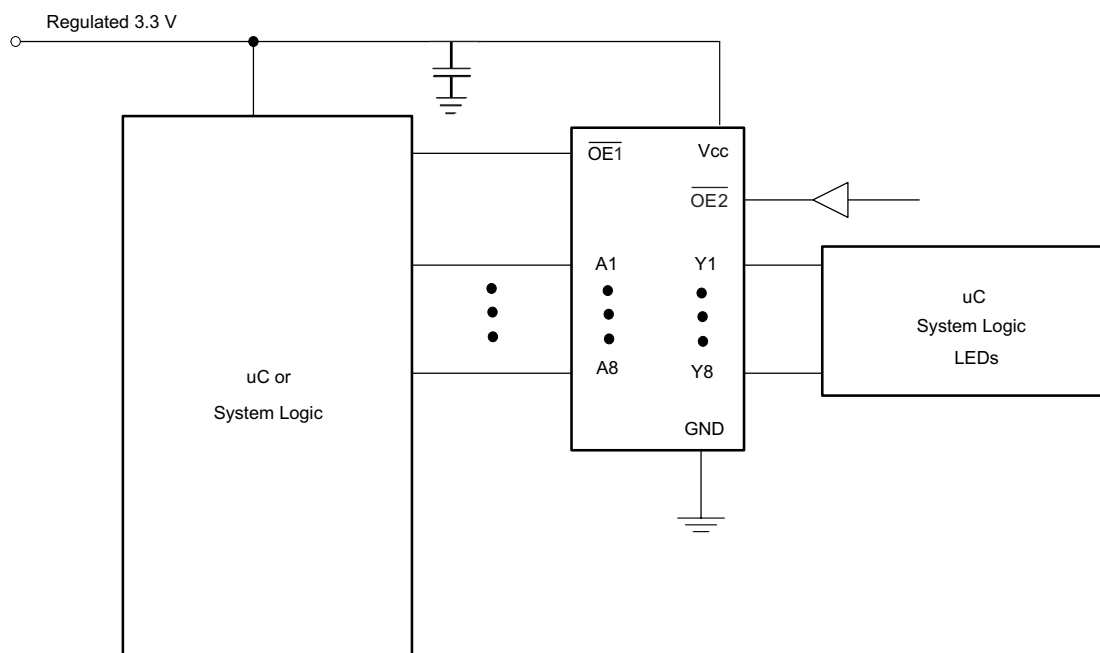


Figure 4. Typical Application Diagram

10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
 - Rise time and fall time specs: See $(\Delta t/\Delta V)$ in the [Recommended Operating Conditions](#) table.
 - Specified high and low levels: See $(V_{IH}$ and $V_{IL})$ in the [Recommended Operating Conditions](#) table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
2. Recommend Output Conditions
 - Load currents should not exceed 25 mA per output and 50 mA total for the part.
 - Outputs should not be pulled above V_{CC} .

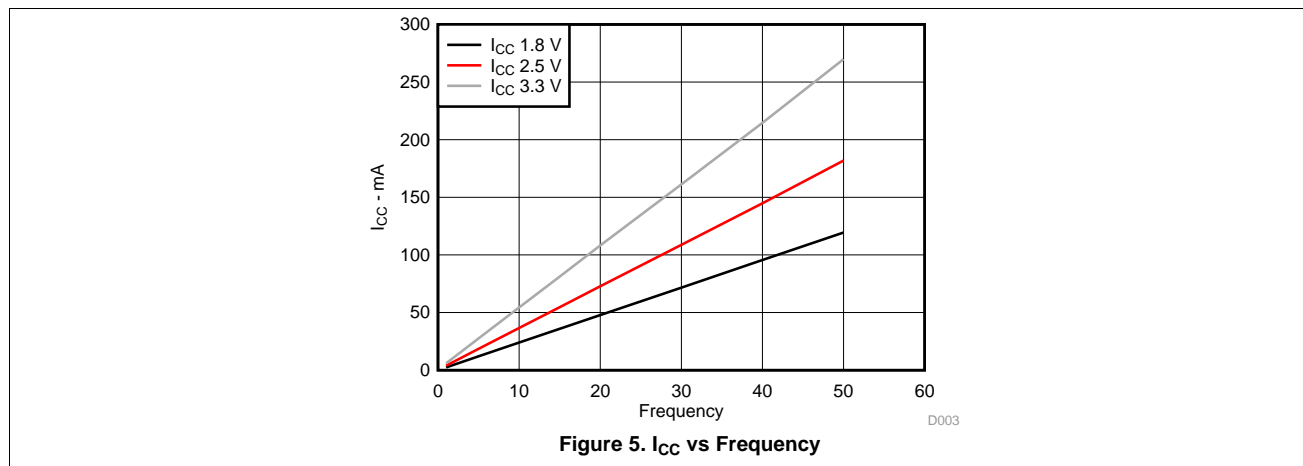
SN54LVC541A, SN74LVC541A

SCAS298N – JANUARY 1993 – REVISED JUNE 2014

www.ti.com

Typical Application (continued)

10.2.3 Application Curves



11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 µf is recommended; if there are multiple V_{CC} pins, then 0.01 µf or 0.022 µf is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 µf and a 1 µf are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

12 Layout

12.1 Layout Guidelines

When using multiple bit logic devices inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. [Figure 6](#) specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the output section of the part when asserted. This will not disable the input section of the I/Os, so they cannot float when disabled.

12.2 Layout Example

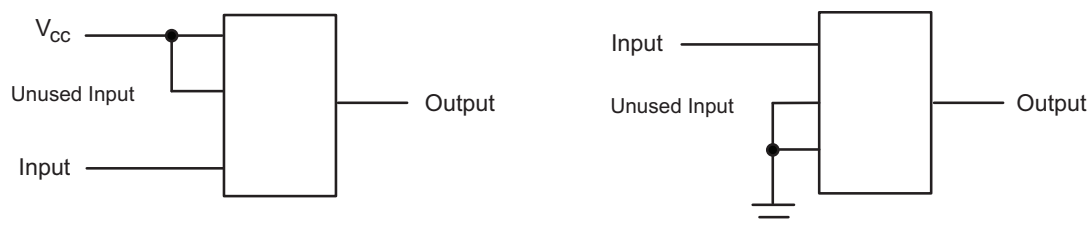


Figure 6. Layout Diagram

13 Device and Documentation Support

13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|-------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| SN54LVC541A | Click here | Click here | Click here | Click here | Click here |
| SN74LVC541A | Click here | Click here | Click here | Click here | Click here |

13.2 Trademarks

All trademarks are the property of their respective owners.

13.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|---------------------------------------|-------------------------|
| 5962-9759501Q2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-9759501Q2A SNJ54LVC 541AFK | Samples |
| 5962-9759501QRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9759501QR A SNJ54LVC541AJ | Samples |
| 5962-9759501QSA | ACTIVE | CFP | W | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9759501QS A SNJ54LVC541AW | Samples |
| SN74LVC541ADBLE | OBSOLETE | SSOP | DB | 20 | | TBD | Call TI | Call TI | -40 to 85 | | |
| SN74LVC541ADBR | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541ADBRG4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541ADGVR | ACTIVE | TVSOP | DGV | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541ADGVRE4 | ACTIVE | TVSOP | DGV | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541ADGVRG4 | ACTIVE | TVSOP | DGV | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541ADW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC541A | Samples |
| SN74LVC541ADWG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC541A | Samples |
| SN74LVC541ADWR | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC541A | Samples |
| SN74LVC541ADWRE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC541A | Samples |
| SN74LVC541ANSR | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC541A | Samples |
| SN74LVC541APW | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541APWE4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|---|-------------------------|
| SN74LVC541APWG4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541APWLE | OBSOLETE | TSSOP | PW | 20 | | TBD | Call TI | Call TI | -40 to 85 | | |
| SN74LVC541APWR | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU CU SN | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541APWRE4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541APWRG4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541APWT | ACTIVE | TSSOP | PW | 20 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC541A | Samples |
| SN74LVC541ARGYR | ACTIVE | VQFN | RGY | 20 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | LC541A | Samples |
| SN74LVC541ARGYRG4 | ACTIVE | VQFN | RGY | 20 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | LC541A | Samples |
| SNJ54LVC541AFK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 9759501Q2A SNJ54LVC 541AFK | Samples |
| SNJ54LVC541AJ | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9759501QR A SNJ54LVC541AJ | Samples |
| SNJ54LVC541AW | ACTIVE | CFP | W | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9759501QS A SNJ54LVC541AW | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.



Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVC541A, SN74LVC541A :

- Catalog: [SN74LVC541A](#)
- Automotive: [SN74LVC541A-Q1](#), [SN74LVC541A-Q1](#)
- Enhanced Product: [SN74LVC541A-EP](#), [SN74LVC541A-EP](#)
- Military: [SN54LVC541A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects



www.ti.com

Distributor of Texas Instruments: Excellent Integrated System Limited

Datasheet of SN74LVC541ADBR - IC BUFF/DVR TRI-ST 8BIT 20SSOP

Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com

PACKAGE OPTION ADDENDUM

16-Jul-2014

-
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
 - Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

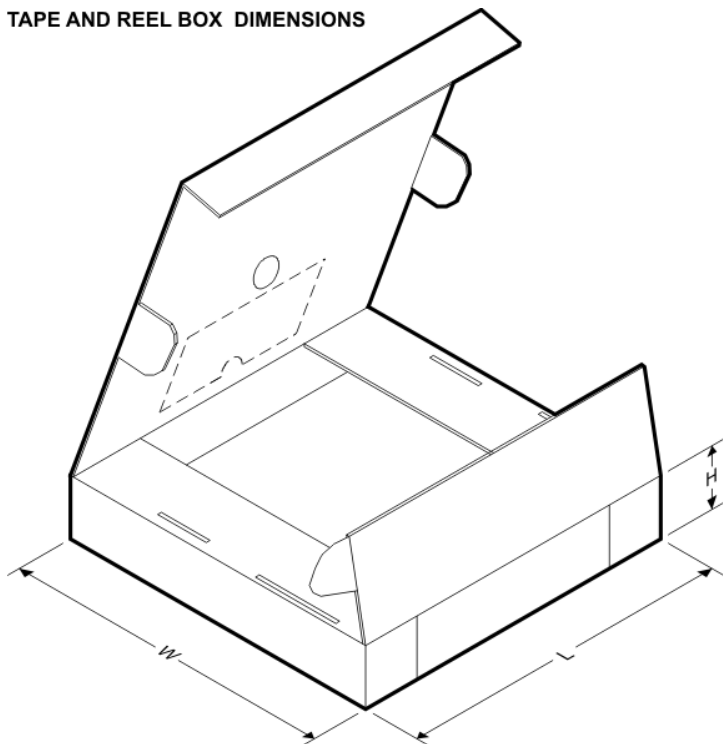
TAPE AND REEL INFORMATION



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC541ADBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVC541ADGVR | TVSOP | DGV | 20 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC541ADWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74LVC541ANSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 9.0 | 13.0 | 2.4 | 4.0 | 24.0 | Q1 |
| SN74LVC541APWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| SN74LVC541APWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| SN74LVC541APWT | TSSOP | PW | 20 | 250 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| SN74LVC541ARGYR | VQFN | RGY | 20 | 3000 | 330.0 | 12.4 | 3.8 | 4.8 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



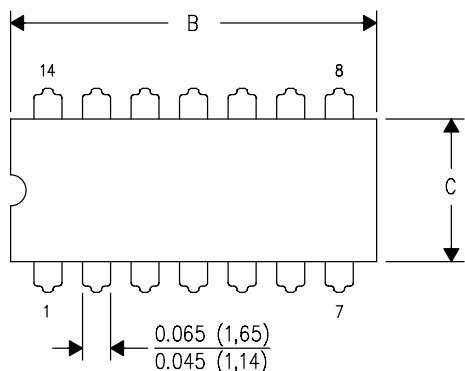
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC541ADBR | SSOP | DB | 20 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LVC541ADGVR | TVSOP | DGV | 20 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74LVC541ADWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74LVC541ANSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74LVC541APWR | TSSOP | PW | 20 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LVC541APWR | TSSOP | PW | 20 | 2000 | 364.0 | 364.0 | 27.0 |
| SN74LVC541APWT | TSSOP | PW | 20 | 250 | 367.0 | 367.0 | 38.0 |
| SN74LVC541ARGYR | VQFN | RGY | 20 | 3000 | 367.0 | 367.0 | 35.0 |

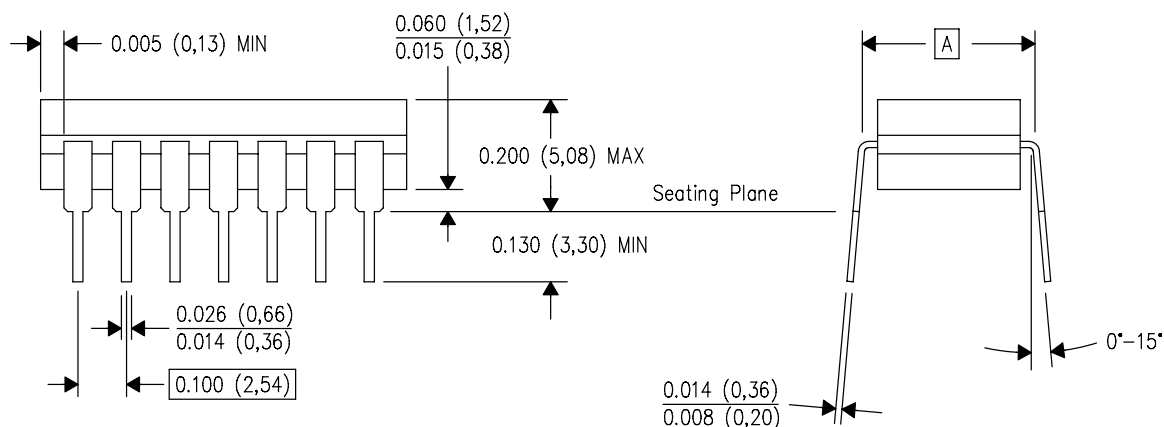
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| PINS ** | 14 | 16 | 18 | 20 |
|---------|------------------------|------------------------|------------------------|------------------------|
| DIM | | | | |
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



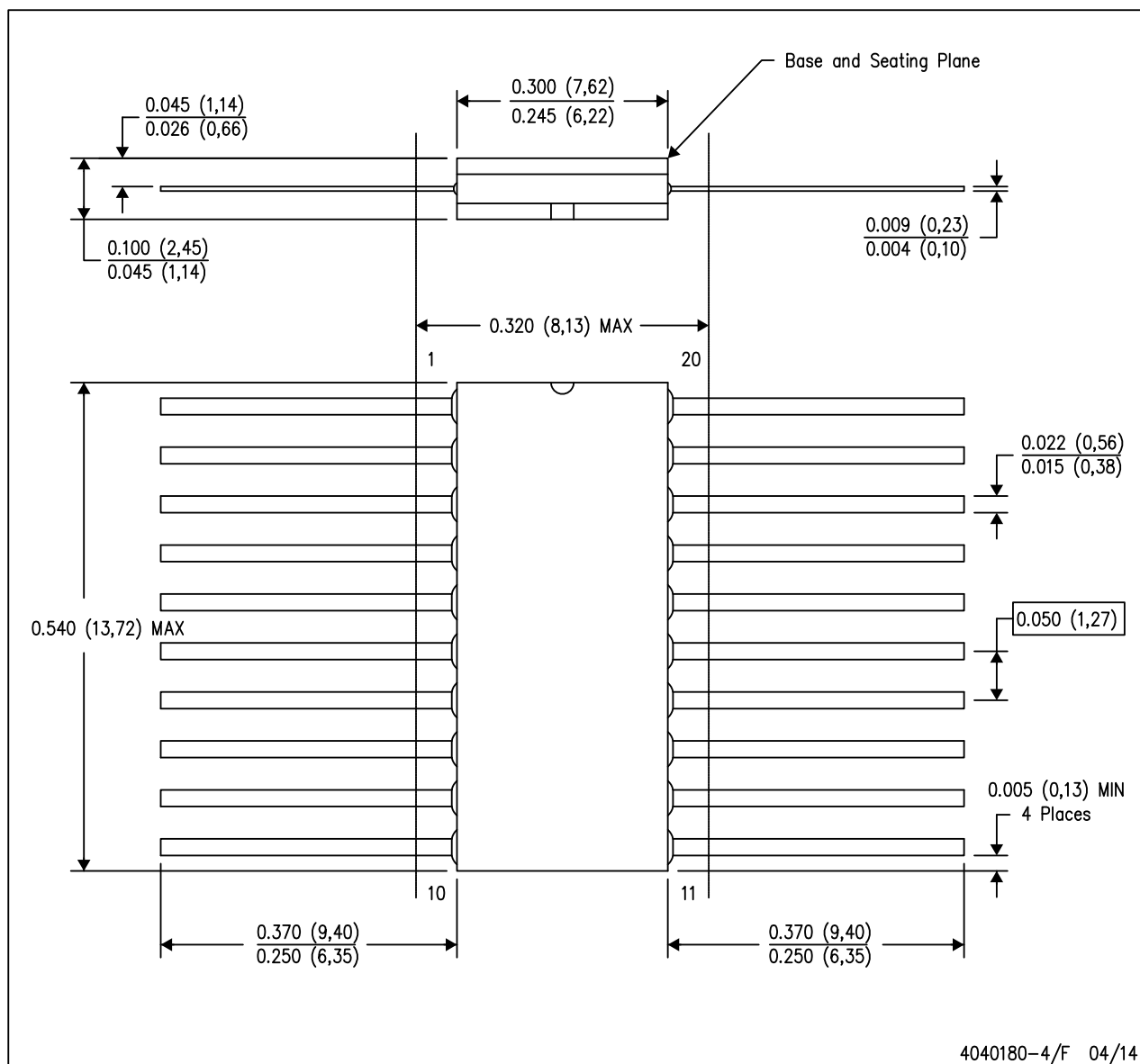
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

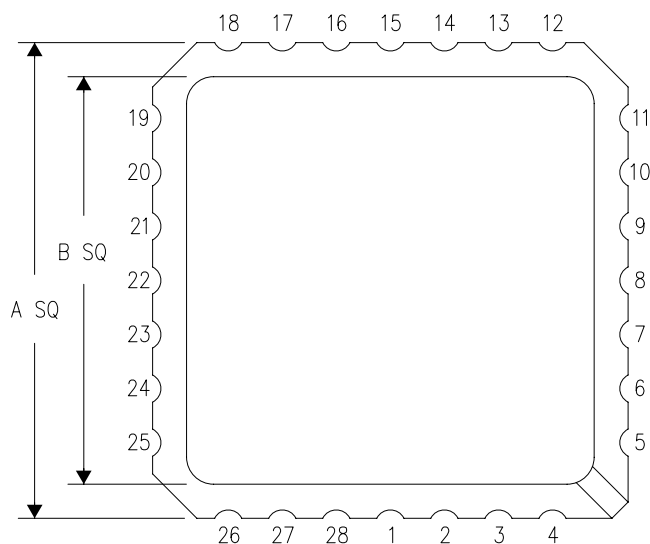


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

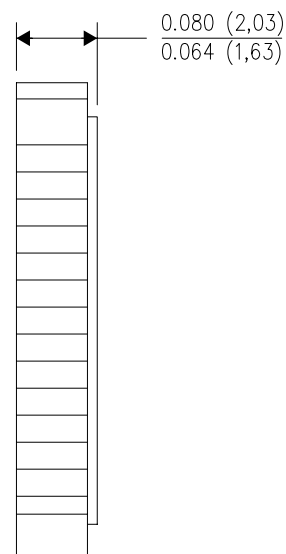
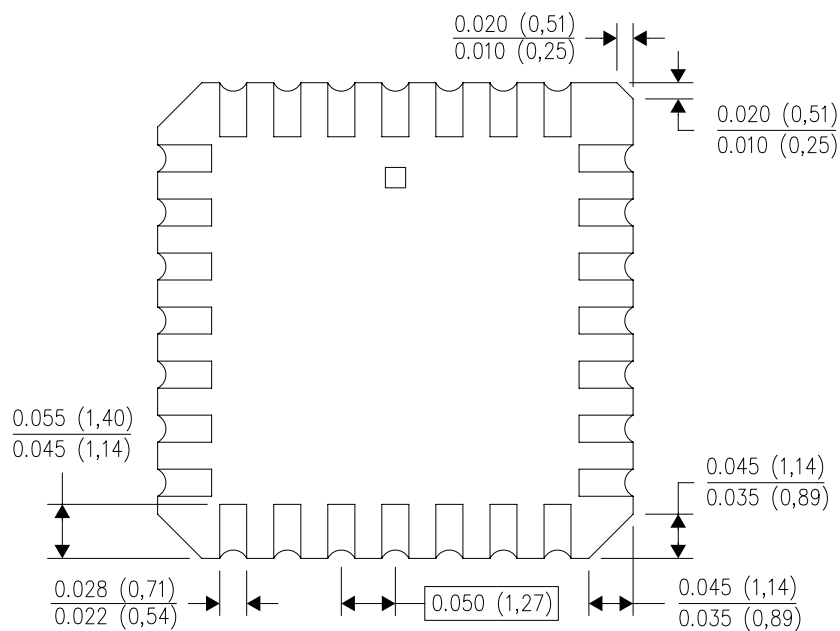
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



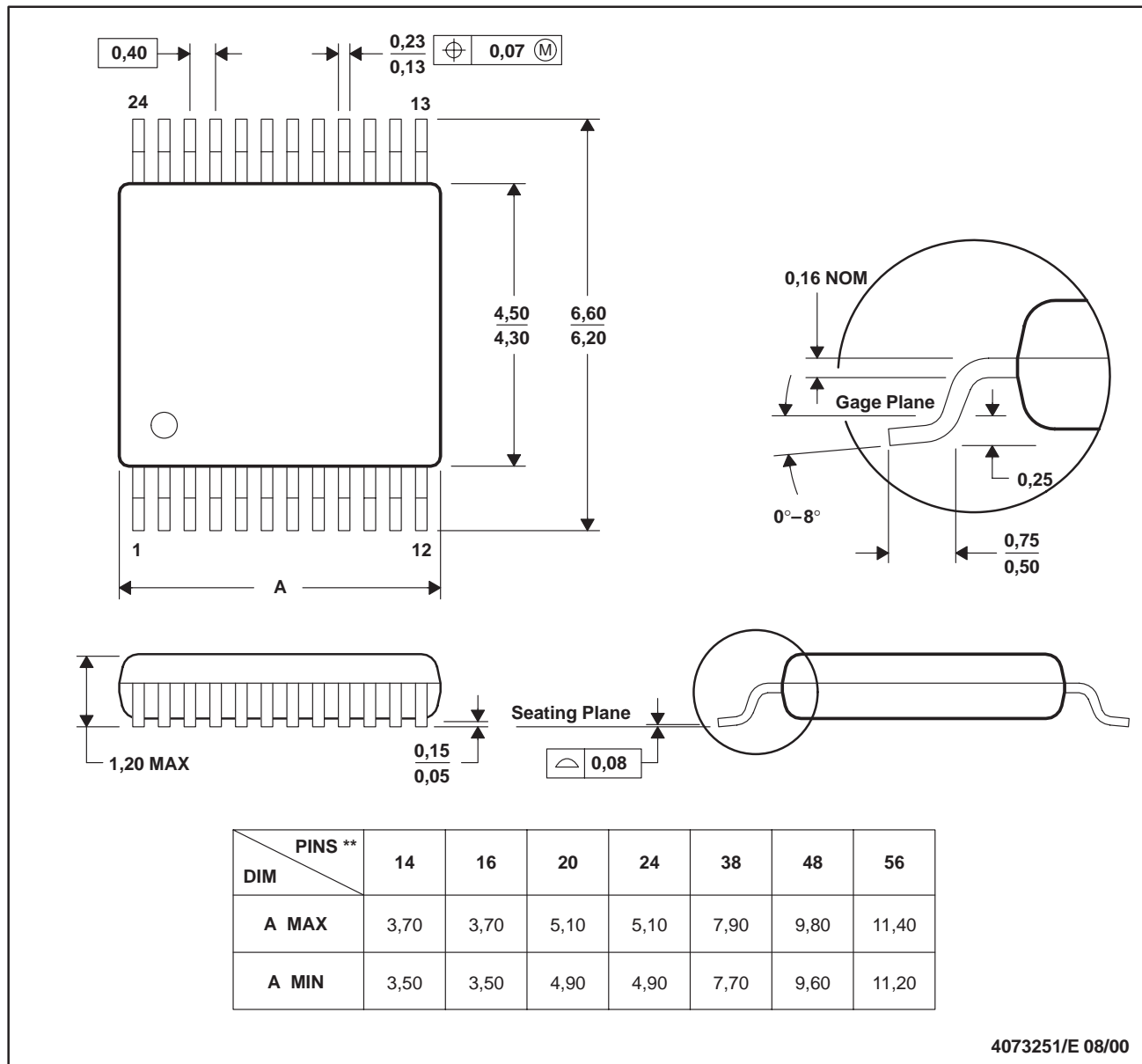
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

DGV (R-PDSO-G)**

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

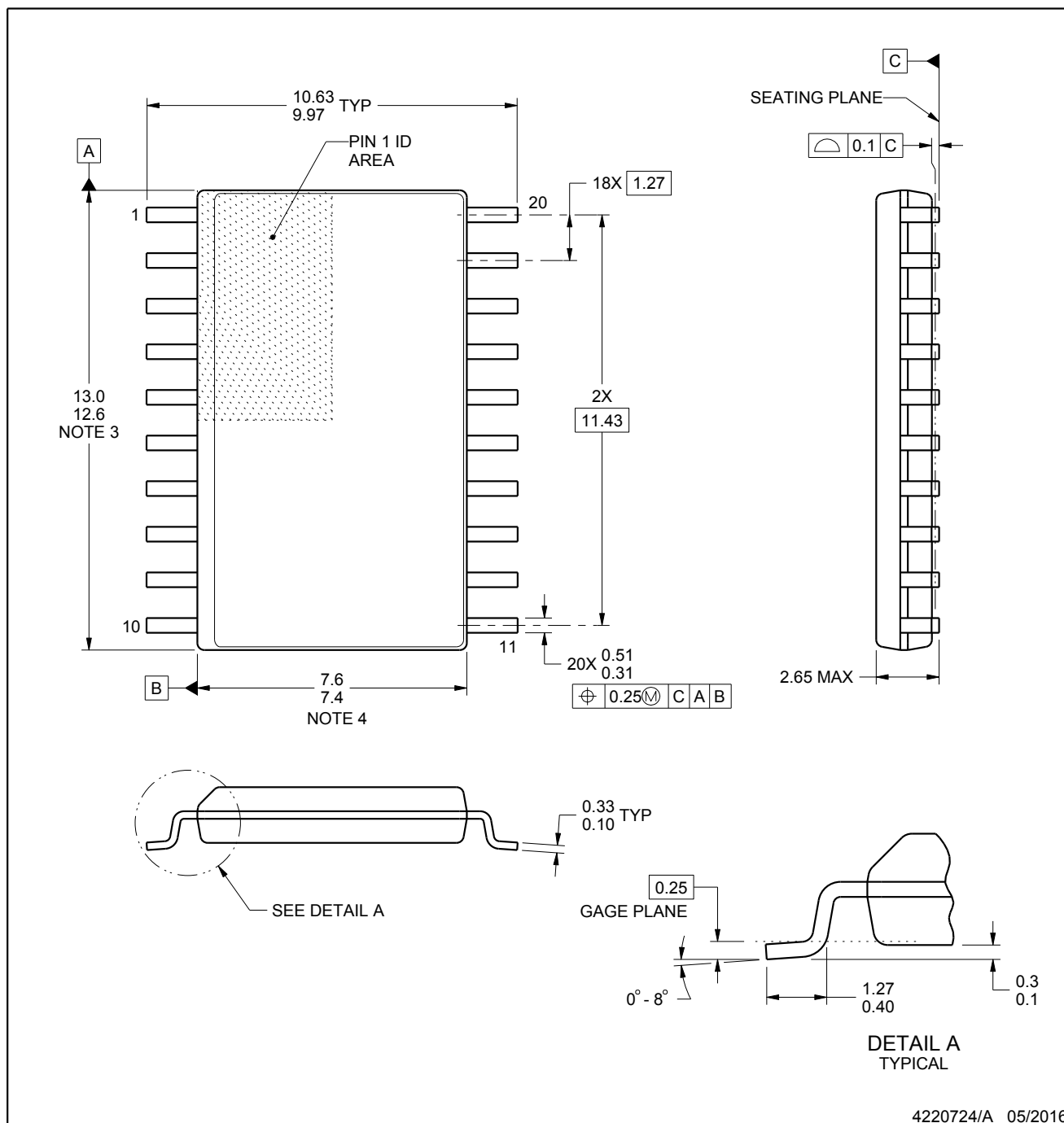


PACKAGE OUTLINE

DW0020A

SOIC - 2.65 mm max height

SOIC



NOTES:

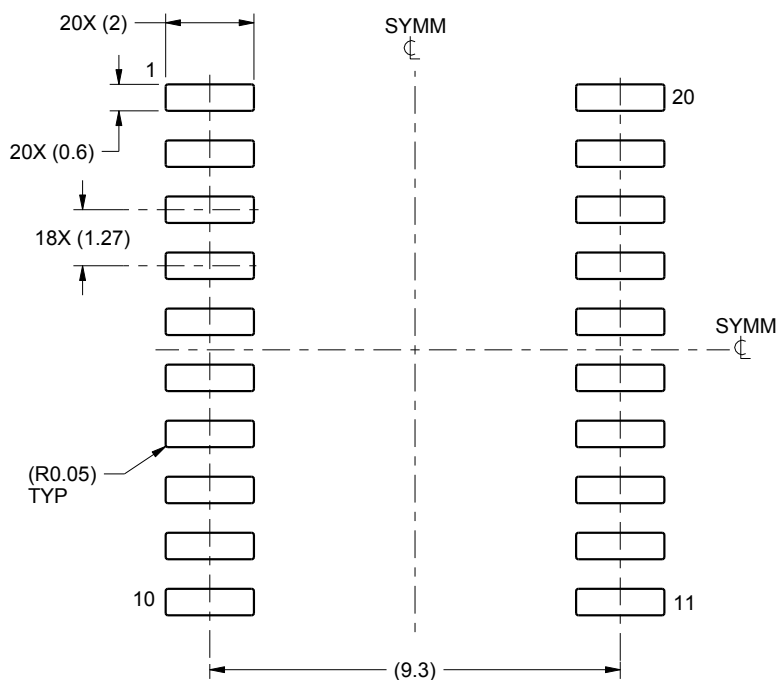
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

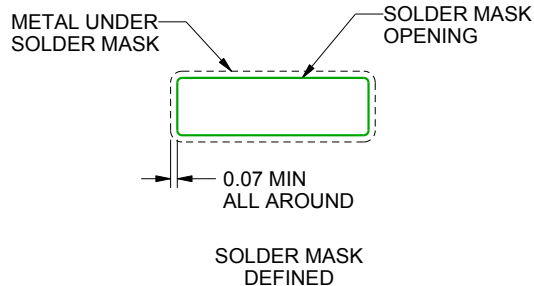
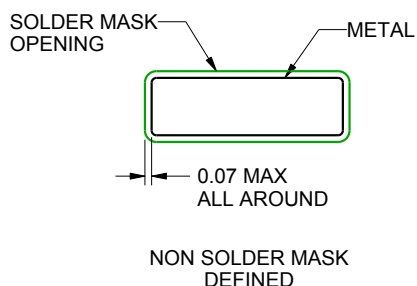
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

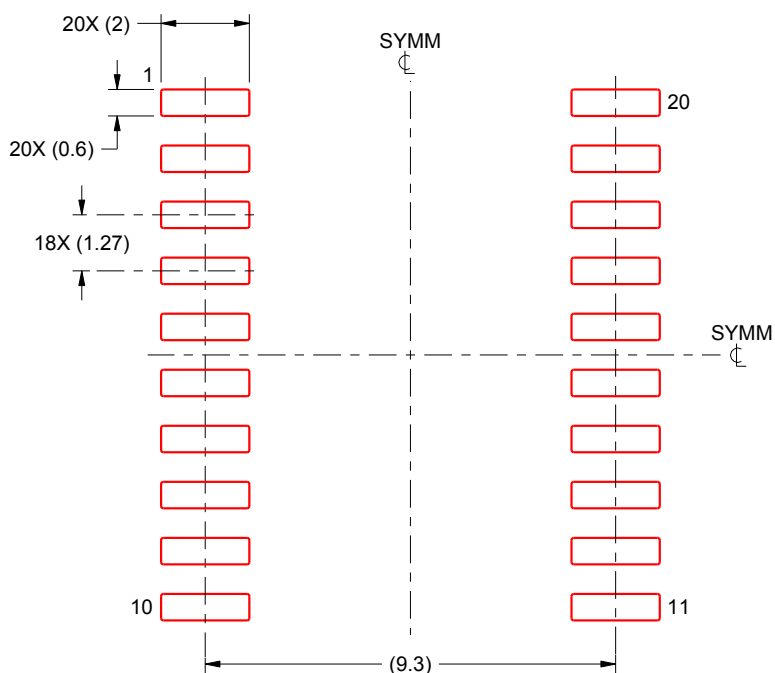
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

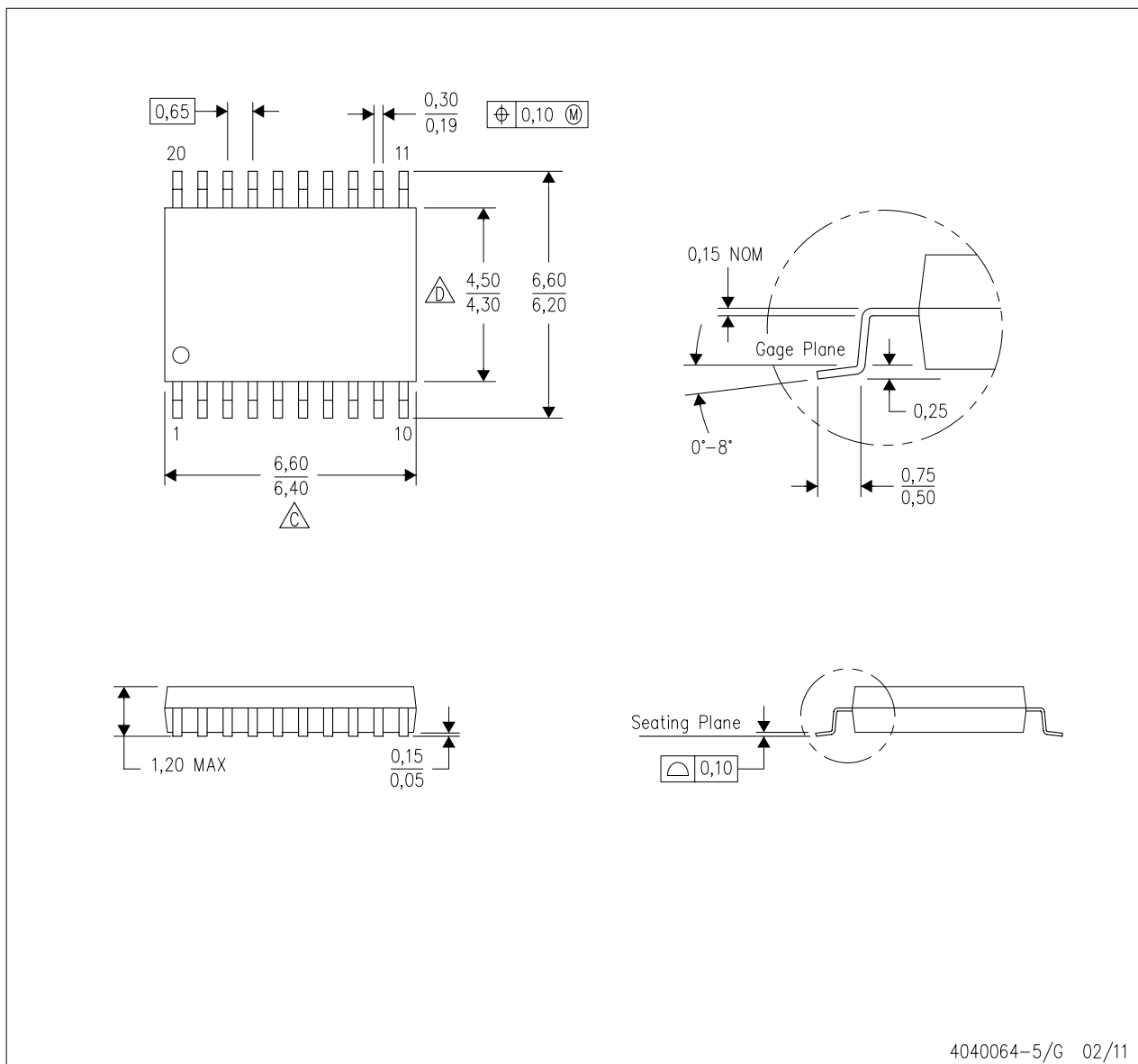
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

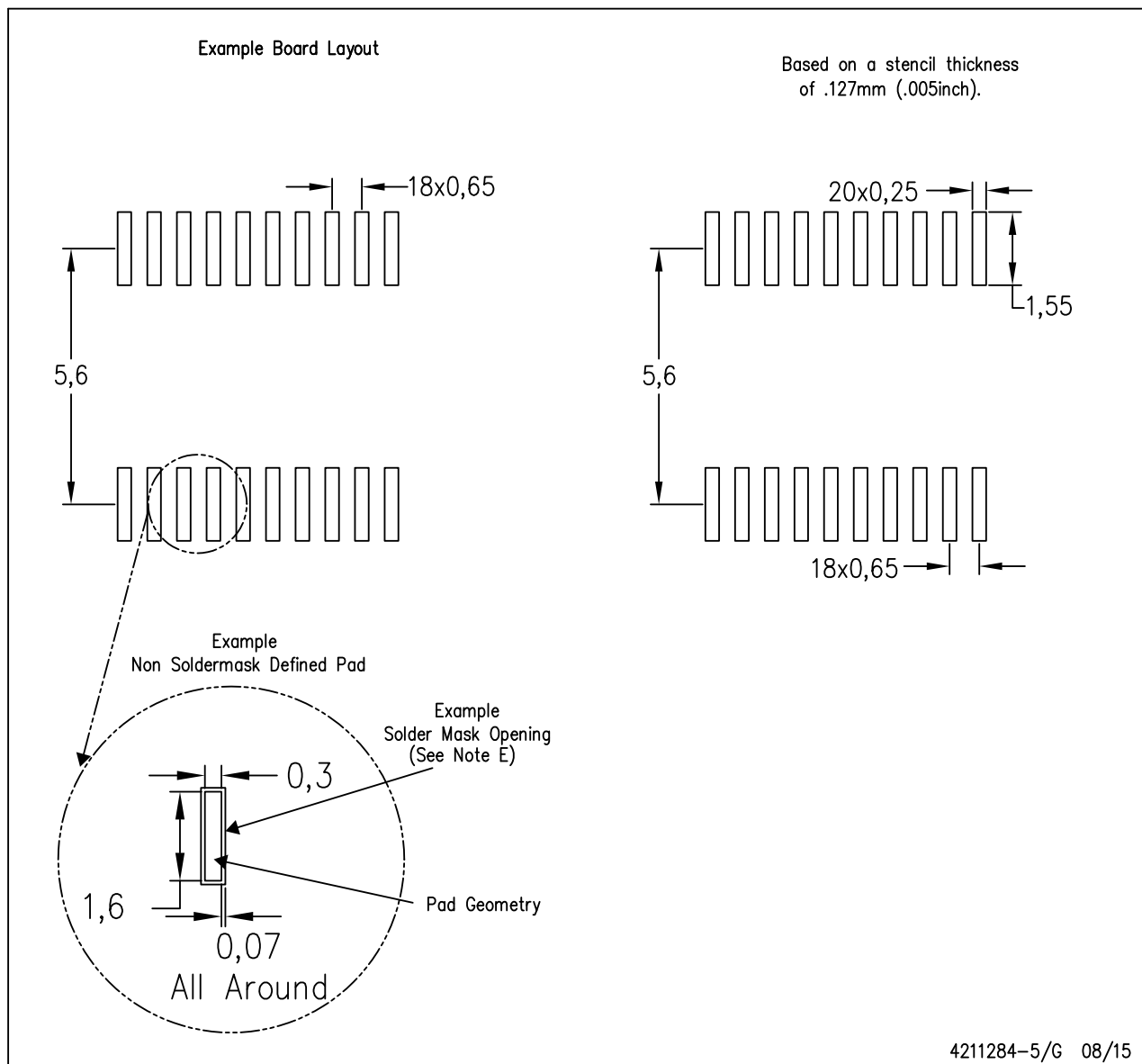


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

LAND PATTERN DATA

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4211284-5/G 08/15

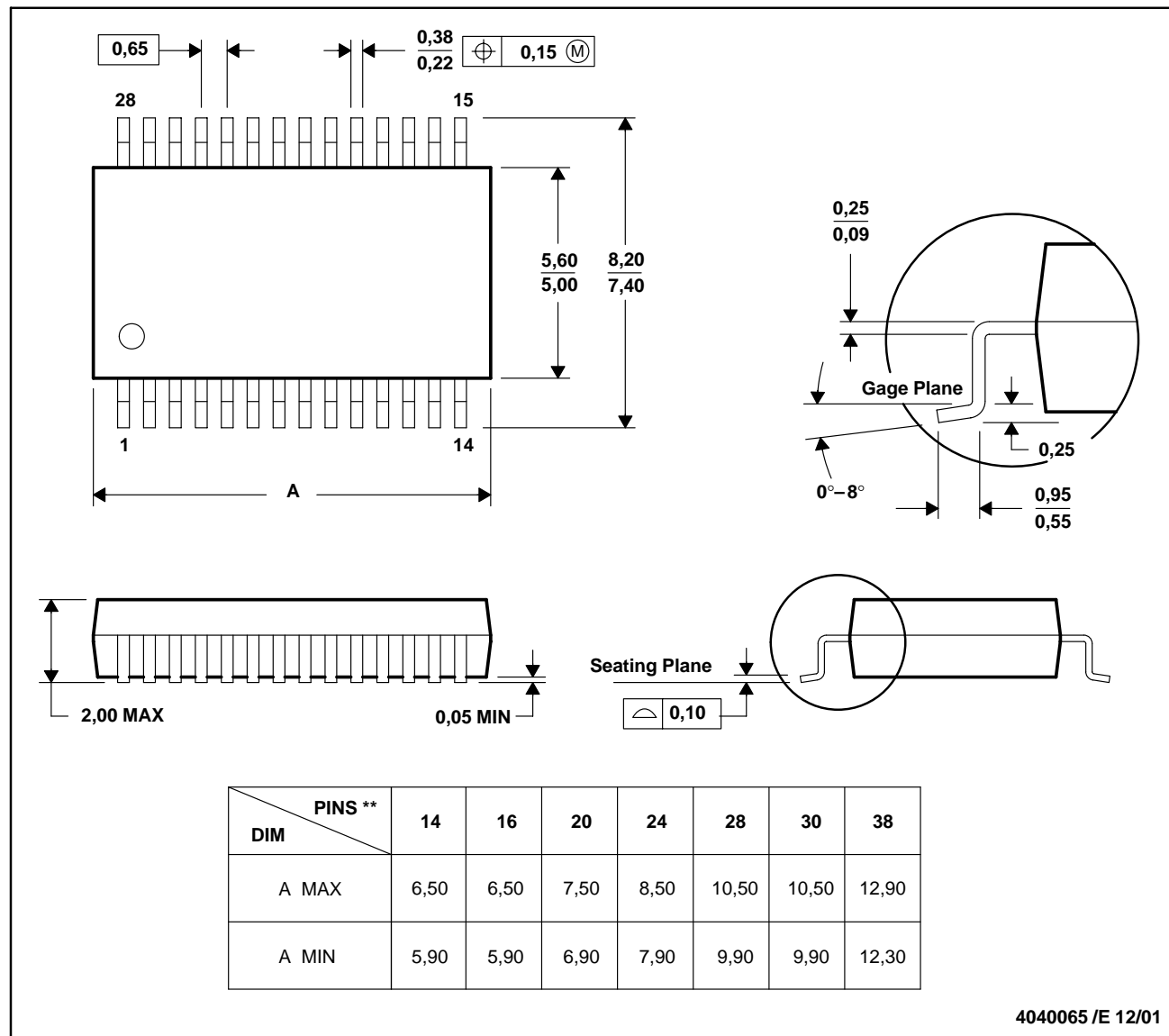
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)**

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150



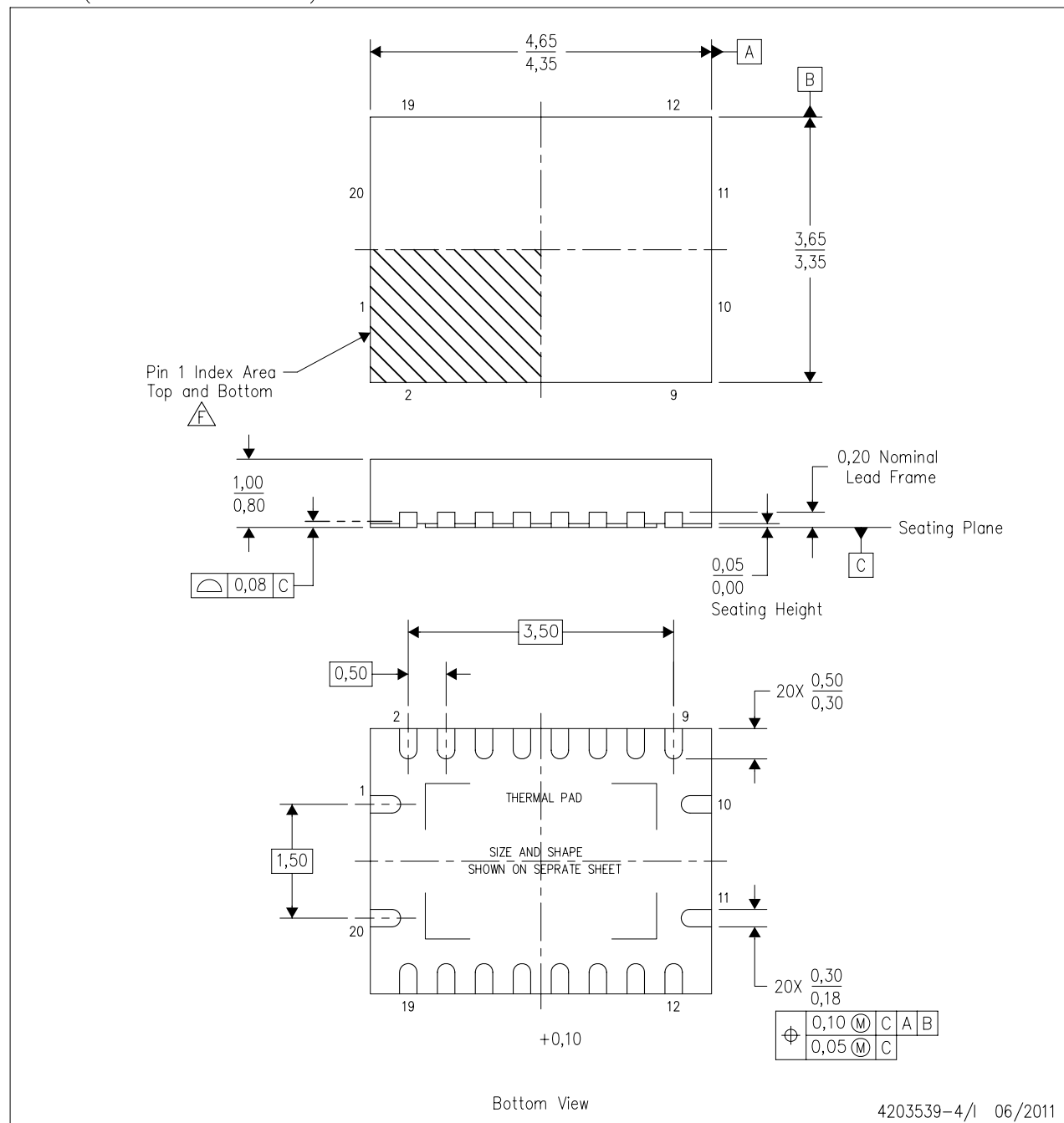
**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

MECHANICAL DATA

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - △ Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.
The Pin 1 identifiers are either a molded, marked, or metal feature.
 - Package complies to JEDEC MO-241 variation BA.

THERMAL PAD MECHANICAL DATA

RGY (R–PVQFN–N20)

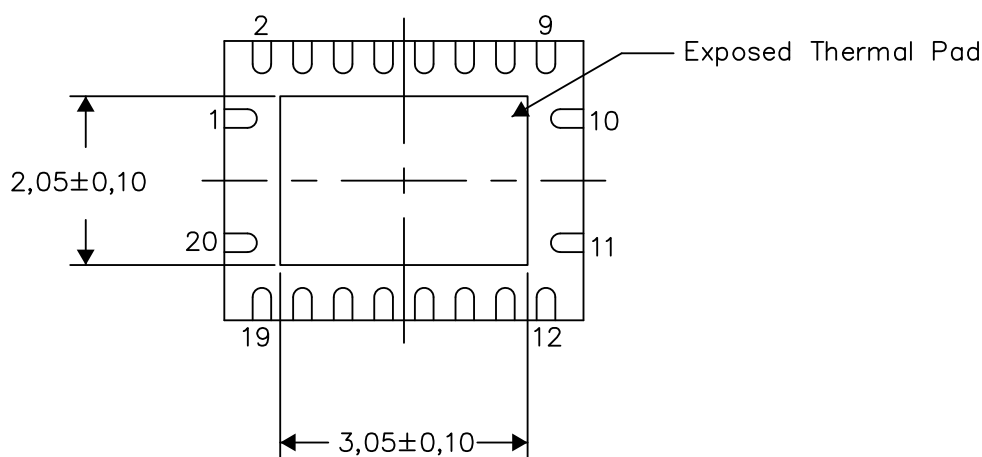
PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

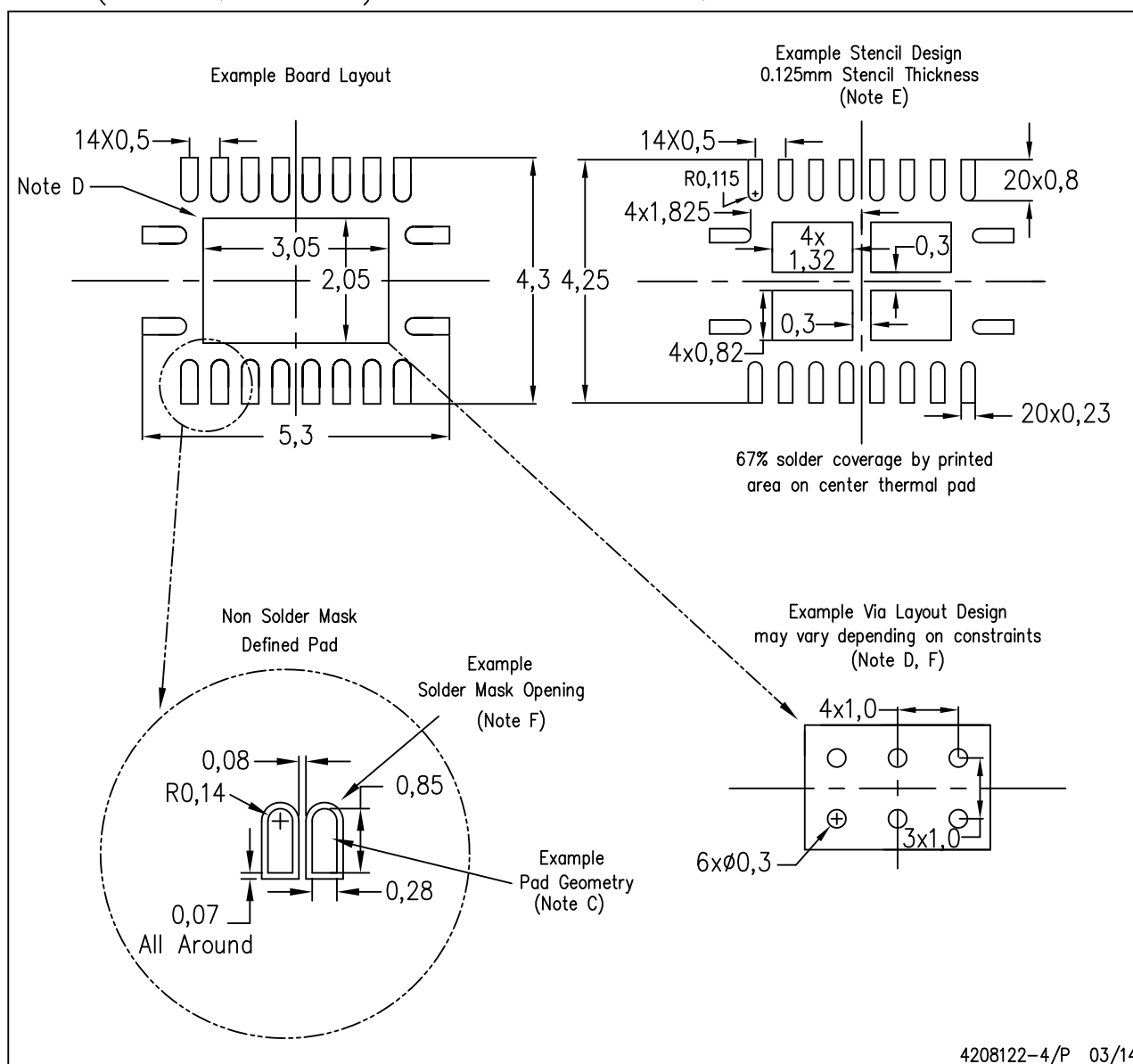
4206353–4/P 03/14

NOTE: All linear dimensions are in millimeters

LAND PATTERN DATA

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-4/P 03/14

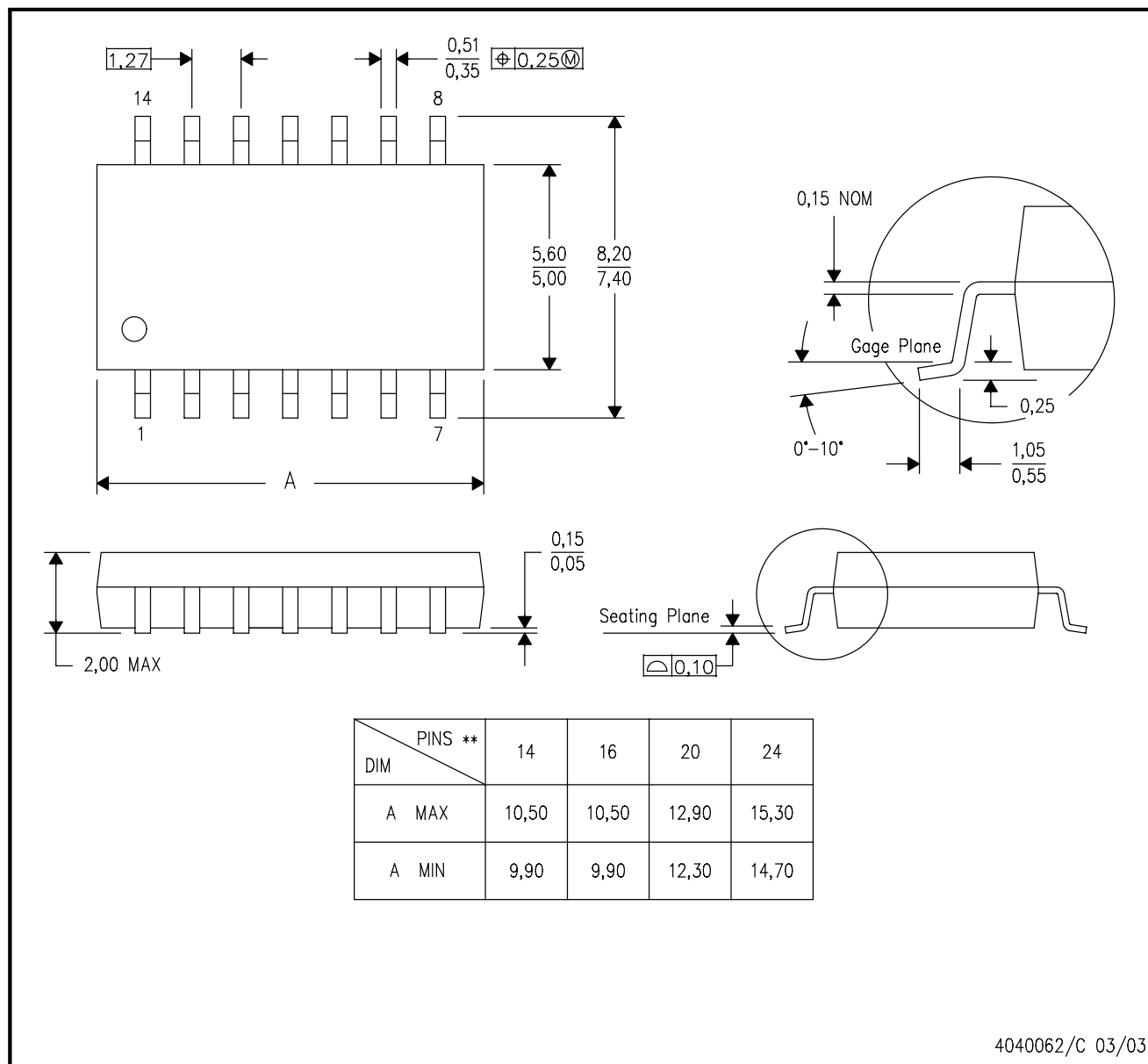
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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